

[one or more] a plurality of electrically conductive contact pads integral with said matrix,
said pads each in electrical contact with a plurality of conductive pathways, wherein at least a
portion of one or more of said pads is flush with or extends outward from an [one or more of
said] outer surface[s] of said matrix[, and wherein at least a portion of said pad is in at least
intimate contact with one or more of said pathways].

REMARKS

The applicant does not understand what may comprise a title which the examiner feels is
better than the existing title. It seems that the title closely matches the preamble of claim 1.
Accordingly, the title has not been amended. If the examiner can suggest a more appropriate
title, the applicant will consider this.

The examiner rejected all of the claims in issue as anticipated by or obvious over Jin et al
5,618,189. Jin discloses a solder-based medium for interconnecting circuits. As described in the
abstract, solder wires or solder-coated particles are embedded in an insulating matrix. The
matrix is then used to interconnect meeting pads of devices. An embodiment using wires is
shown interconnecting meeting pads of devices in figure 5. The embodiment with particles is
shown in a similar fashion in figure 9. In an alternative, the insulating matrix can be dissolved
after the interconnection is made to leave just the solder wires or solder-coated particles, as
shown in figures 6 and 10 respectively.

Jin does not disclose or suggest the invention of claim 1. Claim 1 includes electrically
conductive contact pads that are integral with the matrix and each electrical contact with a
plurality of conductive pathways. Such an elastomeric interconnect device is not disclosed in
Jin. In Jin, the elastomeric interconnect device has no pads. Rather, the external surface of the
device is shown best in figures 5 and 8 have either the wires or column of particles projecting


from the matrix surfaces. There are no conductive contact pads integral with the matrix and in electrical contact with the pathways.

Jin does not place any pads on the matrix. Indeed, as shown in figures 5 and 9, the pads of the circuit boards or the like that are interconnected with the Jin interconnect structure clearly do not touch the matrix. Accordingly, they are not even integral with the matrix after the assembly has been completed. Just as importantly, the Jin interconnect device includes no pads. Instead, the interconnect device is soldered to pads of meeting devices such as devices 53 and 55, figure 5, or 93 and 94, figure 9. Accordingly, the Jin reference has all of the problems recited in the background of the subject application, and does not disclose or suggest the construction or the objects of the claimed invention.

Each of the dependent claims currently under consideration add further limitations that are not disclosed or suggested by Jin in combination with claim 1. Accordingly, each of the dependent claims is also patentable.

If for any reason this Response is found to be incomplete, or if at any time it appears that a telephone conference with counsel would help advance prosecution, please telephone the undersigned in Westborough, Massachusetts, (508) 898-1501.

Respectfully submitted,



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